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1. PRODUCT IDENTITY AND POSITIONNING



	Key points		Unit design
		3D Cone Beam Lightest on market	Owandy
JEV	v!	Wall mounted concept	I-nax [®]
	3D x16	Multi-FOV: 12x10*, 9x9 to 5x5 cm 16 3D programs	asse of the state
	HD B	HD : 87 μm Face to face positioning	
		3D digital models	
JEV	FACE SCAN	The best Investment/Performance ratio	
JEV	SCAN	Face Scan Ready	

^{*} F.O.V 12x10cm in option (P/N EXTVOL3D12x10)

I-MAX 3D Product launch document – EN

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Main competitors advantages 1. Multi FOV 3D Cone Beam	Can be adapted for use with all kinds of dental practices
1. Walti Tov 3D colle bealth	• Implantology:
	 116x102 mm full mouth and condyles (in option)
	- 86x93mm full mouth
	- 86x50mm full arch
	Endodontic: 50x50mm
	Endodontic. 30x30mm
2. HD images	• 3D sensor resolution : voxel 87.5 μm (smallest cross-section)
3. 16 3D programs	Full dental volume & condyles (in option)
	Full dental volume
	 Left / right TMJ
	• Sinus
	 Maxillary volume / Mandibular volume
	Frontal maxillary teeth
	 Left / right premolar maxillary teeth
	 Left / right molar maxillaryt eeth
	Frontal mandibular teeth
	 Left / right premolar mandibular teeth
	 Left / right molar mandibular teeth
4. Lightweight and sophisticated design	The lightest 3D panoramic unit on the market: 66,5kg
	Install it on a wall as your intraoral generator
	Takes up zero floor space
	Stylish: makes surgery look good to patients
5. Easy to use	"Face-to-face" patient positioning
•	Easy to handle equipment
	Intuitive user interface
	 Imaging tools and enhancing filters automatically integrated into the control software.
6. Quick and easy to install in your	Lightweight and compact unit delivered as one single package
surgery	• Exclusive "Easy-To-Install" system: the unit is delivered fully
	assembled with an "intelligent" system, requiring just one techniciar to fix it easily to the wall
7 Controlled budget	Unit optimised for manufacturing
7. Controlled budget	Lower installation costs, economical shipping costs
	The best Investment / Performance ratio
8. Face Scan ready *	Communication with patients facilitated: he will project himself more
	easily, to accept the suggested treatment plan
* OBJ or .PLY file must come from a third-party device	Increases confidence in your expertise and know-howImport .OBJ and .PLY files
9. CAD / CAM ready	 Scan of 3D models: impression trays, plaster models and radiologica guides



I-MAX 3D Product launch document – EN

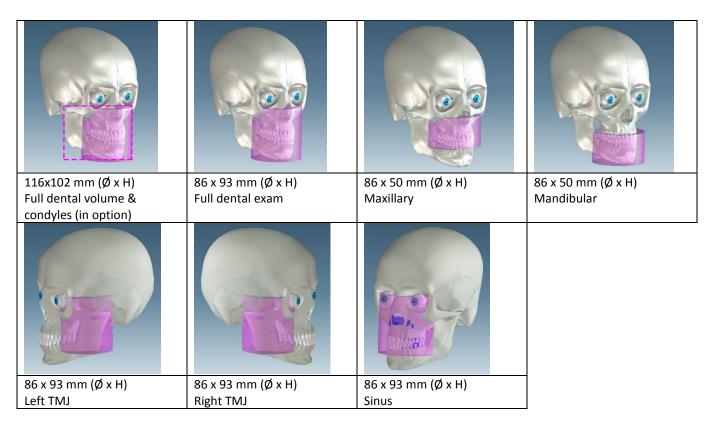
LD_IMAX3D_EN_REV04 Page 5 sur 30

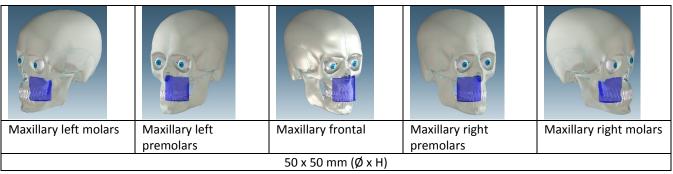
10. Surgical guides

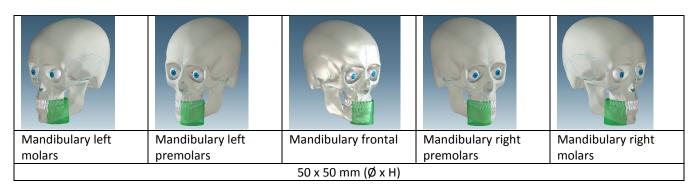
- Superposition of STL and DICOM files
- Thanks to the I-Max 3D / Quickvision 3D couple, you can create surgical guides in total autonomy



FOCUS: 16 multi FOV 3D programmes:









2. TECHNICAL CHARACTERISTICS

General features		
Manufacturer	OWANDY RADIOLOGY 77183 Croissy-Beaubourg, France	
Class II-b for European Directive for Medical Devices 93/42 Class I with type B applied parts according to IEC 60601-1 Class II for Canadian MDR Class II according to 21CFR-subchapter J (for 110-120V version)		
Protection degree	IPX0 standard device	
Line frequency	50/60Hz	
Maximum line current	14.5 A @ 115 V~ 50/60 Hz	
Power consumption	1.5 kVA @ 115 V~ 50/60 Hz 1.3 kVA @ 230 V~ 50/60 Hz	
Line apparent resistance	0.4 Ω max (99 – 132 V) 0.5 Ω max (198 – 264 V)	
Line voltage regulation	< 3% à 99 V ~	
Rated output voltage (kVp)	60 ÷ 86 kV, with 2 kV steps	
Anodic current	2 ÷ 12.5 mA, according to r20 scale	
Mechanical characteristics		
Focal spot to image receptor distance	52 cm (20.5")	
Telescopic motorized column run	66 cm (26")	
Maximum total height	219 cm (86")	
Weight (complete unit, wall mounted version)	67 kg	
Weight of optional unit support	6 kg	
Working conditions		
Minimum room size	120x115cm (47.2"x45.2")	
Recommended room size	160x150cm (63"x59")	
Unit footprint dimensions (mm)	1107(wall side) x 953mm = 1m²	
Maximum working temperature range	+ 10° ÷ + 35°	
Relative working humidity (RH) range	30% ÷ 75%	
Temperature range for transport and storing	- 20° ÷ + 70°	
Humidity range for transport and storing	< 95% without condensation	
Minimum atmospheric pressure for transport and storing	630 hPa	



3. SENSORS AND XRAY GENERATOR CHARACTERISTICS

transfecturer Section	Tube-head features			
laximum tube voltage with accuracy 12.5 mA ± 10 % 12.5 mA ≥ 2.5 mm Al eq. @ 86 kVp 12.5 mA eq. @ 86 kVp 12.5 mA - 3s duty cycle 1/16 12.5 mA - 1	Model	MPV 05	MPV 05	
taximum anodic current with accuracy 12.5 mA ± 10 % uty cycle 1:16 ominal power 1.075 kW (86 kVp - 12.5 mA) ≥ 2.5 mm Al eq. @ 86 kVp VV. (Half value layer) > 3.2 mm Al eq. @ 86 kVp vansformer insulation Oil bath ooling By convection eakage radiation at 1 m < 0.5 mGy/h @ 86 kVp - 12.5 mA - 3s duty cycle 1/16 ube-head features flanufacturer CEI OPX 105-12 ominal focal spot size O.5 mm EN 60336 sherent filtration 0.5 mm Al eq. node tilt 12° node material ominal maximum voltage 110 kVp lament max current 4 A lament max current 4 A lament max voltage 6.7 V node thermal capacity 30 KJ igital Sensor features ensible area (H x L) CMOS sensor 144 x 118.6 mm oxel 87.5 μm (XD mode) 175 μm (HD mode) ixel (H) 120 μm 240 μm (2x2 binning) aser centering devices laser beams are used for patient positioning. Beams align mid Sagittal and Frankfurt planes. Class 2 laser roduct according to IEC Standard 60825-1:2007. Jave length 650 nm	Manufacturer	Owandy Radiology	Owandy Radiology	
tuty cycle 1:16 ominal power 1.075 kW (86 kVp - 12.5 mA) > 2.5 mm Al eq. @ 86 kVp VV. (Half value layer) > 3.2 mm Al eq. @ 86 kVp vansformer insulation Oil bath ooling By convection eakage radiation at 1 m < 0.5 mGy/h @ 86 kVp - 12.5 mA - 3s duty cycle 1/16 ube-head features flanufacturer CEI ype OPX 105-12 ominal focal spot size 0.5 mm EN 60336 sherent filtration 0.5 mm Al eq. node tilt 12° node material Tungsten ominal maximum voltage 110 kVp llament max current 4 A llament max current 4 A llament max voltage 6.7 V node thermal capacity 30 KJ igital Sensor features ensible area (H x L) CMOS sensor 144 x 118.6 mm oxel 87.5 μm (XD mode) 175 μm (HD mode) ixel (H) 120 μm 240 μm (2x2 binning) aser centering devices laser beams are used for patient positioning. Beams align mid Sagittal and Frankfurt planes. Class 2 laser roduct according to IEC Standard 60825-1:2007. Ave length 650 nm	Maximum tube voltage with accuracy	86 kV ± 8 %	86 kV ± 8 %	
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By convection cakage radiation at 1 m	HVL (Half value layer)	> 3.2 mm Al eq. @ 86 k\	V_p	
cakage radiation at 1 m < 0.5 mGy/h @ 86 kVp - 12.5 mA - 3s duty cycle 1/16 ube-head features Idanufacturer CEI ype OPX 105-12 ominal focal spot size 0.5 mm EN 60336 wherent filtration 0.5 mm Al eq. mode tilt 12° mode material Tungsten ominal maximum voltage 110 kVp idament max current 4 A idament max voltage 6.7 V mode thermal capacity 30 KJ igital Sensor features ensible area (H x L) CMOS sensor 144 x 118.6 mm oxel 87.5 µm (XD mode) 175µm (HD mode) ixel (H) 120 µm 240 µm (2x2 binning) aser centering devices laser beams are used for patient positioning. Beams align mid Sagittal and Frankfurt planes. Class 2 laser roduct according to IEC Standard 60825-1:2007. Jave length 650 nm ivergence < 2.0 mRad	Transformer insulation	Oil bath		
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Ensible area (H x L) CMOS sensor 144 x 118.6 mm 87.5 μm (XD mode) 175μm (HD mode) ixel (H) 120 μm 240 μm (2x2 binning) aser centering devices laser beams are used for patient positioning. Beams align mid Sagittal and Frankfurt planes. Class 2 laser roduct according to IEC Standard 60825-1:2007. //ave length 650 nm ivergence < 2.0 mRad	Anode thermal capacity	30 KJ		
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laser beams are used for patient positioning. Beams align mid Sagittal and Frankfurt planes. Class 2 laser roduct according to IEC Standard 60825-1:2007. Vave length 650 nm ivergence < 2.0 mRad	Voxel	87.5 μm (XD mode)	175μm (HD mode)	
laser beams are used for patient positioning. Beams align mid Sagittal and Frankfurt planes. Class 2 laser roduct according to IEC Standard 60825-1:2007. Vave length 650 nm ivergence < 2.0 mRad	Pixel (H)	120 μm	240 μm (2x2 binning)	
roduct according to IEC Standard 60825-1:2007. /ave length 650 nm ivergence < 2.0 mRad	Laser centering devices			
ivergence < 2.0 mRad	2 laser beams are used for patient positioning. Beams align mid Sagittal and Frankfurt planes. Class 2 laser product according to IEC Standard 60825-1:2007.			
	Wave length	650 nm		
ptical power on the working surface < 1 mW	Divergence	< 2.0 mRad		
	Optical power on the working surface	< 1 mW		



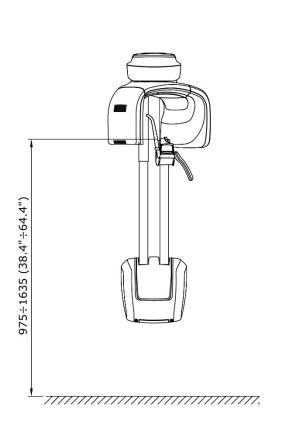
4. COMPUTER CHARACTERISTICS

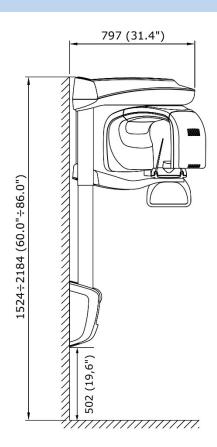
Recommended configuration	
Operating system	Windows 10 - 64 bits
Processor	Core i7 (4 coeurs 8 threads) 3 GHz or higher
Memory	8 Go
Graphic board	nVidia 4 Go (ex : GTX 9 Go)
Main drive	SSD or SATA
Speed network connection practice	1 Gbit
Other	Slot for Ethernet 1 Gbit board (PCI-Express 4X minimum)

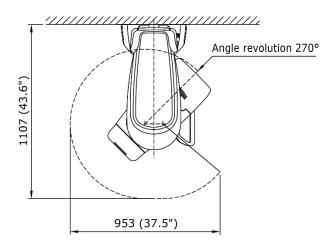


5. UNIT DIMENSIONS

Wall mounted version

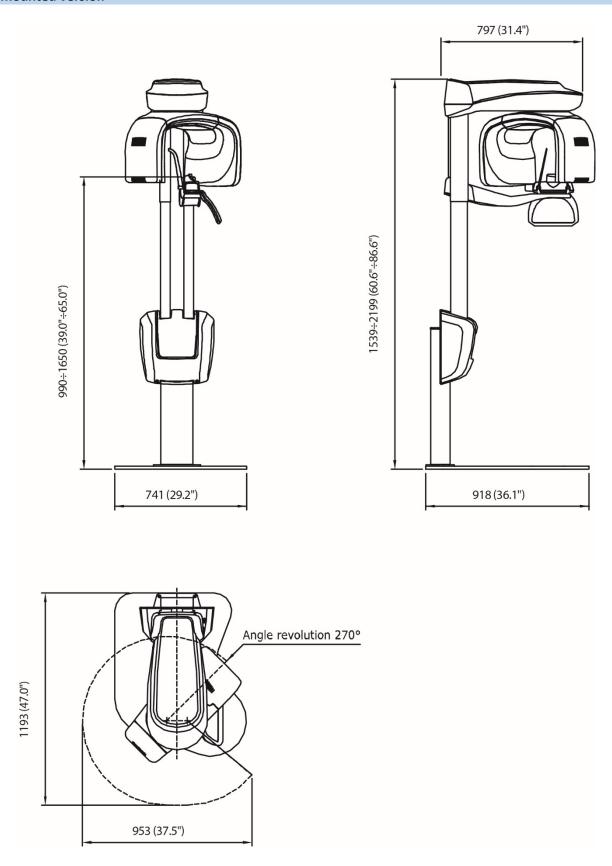








Floor mounted version





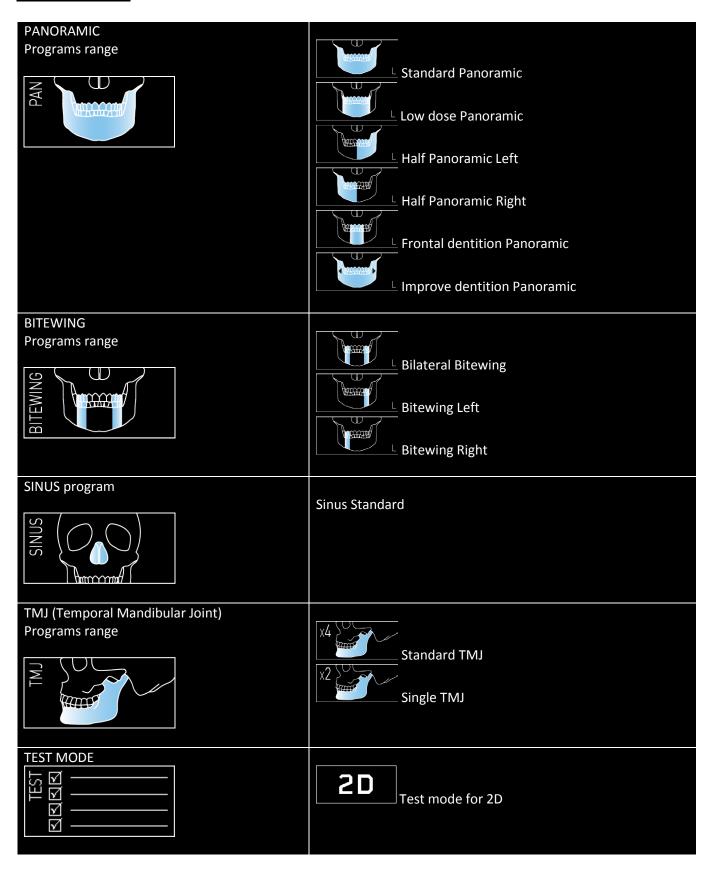
6. 2D EXAMINATION MODES

Exposure time			
Panoramic exam (PAN)	14 s Adult / 12.8 s Child		
Emi-panoramic exam	7.7 s Adult / 7.1 s Child		
Improved orthogonality panoramic exam	11.5 s Adult / Child		
Reduced dose panoramic exam	11.6 s Adult / 10.4 s Child		
Frontal dentition	4.1 s Adult / Child		
Bitewing R, Bitewing L	3.1 s Adult / Child		
Bitewing R&L	6.2 s Adult / Child		
TMJ mouth closed/open	10.6 s per image for left and right joint in open and closed condition		
TMJ single phase	5.3 s		
Sinus P/A projection	9 s		
Image magnification	Geometric magnification	Magnification after software correction	
Adult / Child standard Panoramic	1:1.28 (constant over dentition part)	1:1(*)	
TMJ open/closed mouth	1 : 1.25 (nominal)	1:1(*)	
Sinus	1 : 1.27 (nominal)	1:1(*)	
Programs			
Examination selection type	 Automatic selection for Adult and Child, 3 Sizes Manual selection also possible for each programs Collimator with automatic positioning 		

^(*) The declared image magnification value is valid after proper software calibration.



2D programs



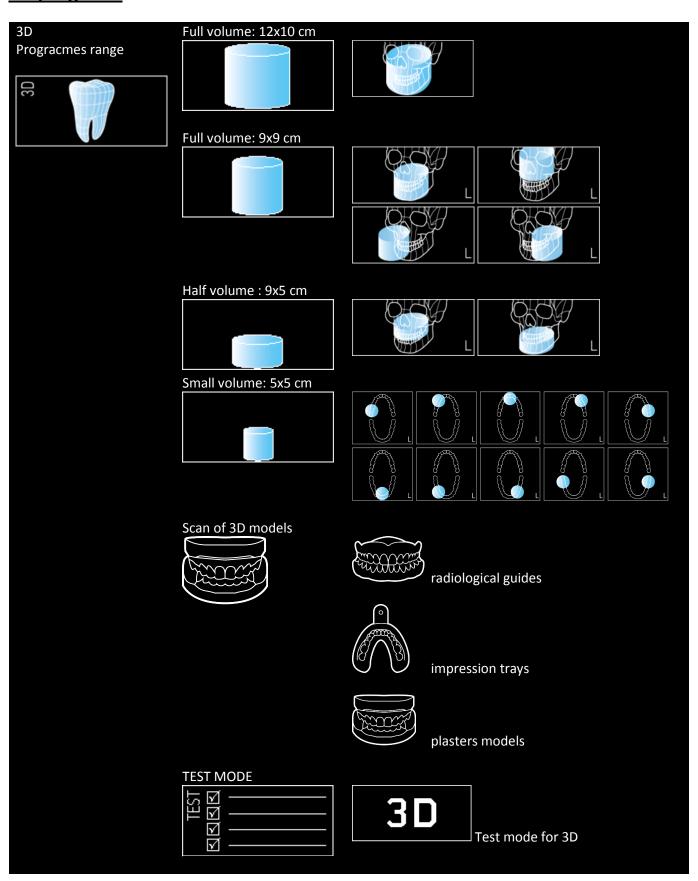


7. 3D EXAMINATION MODES

Exposure time	
3D exams (except TMJ 3D)	7 s
TMJ 3D	6.2 s
Exposure time accuracy	± 5% or ± 20ms whichever is greater



3D programs



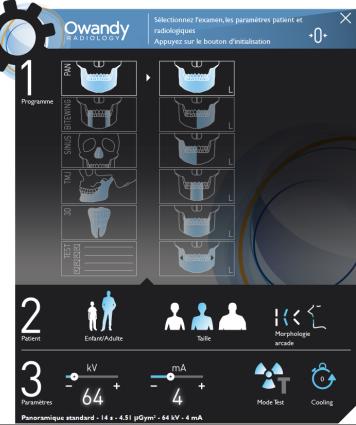


8. USER SOFTWARE INTERFACE

Main settings window: default exam selected automatically..

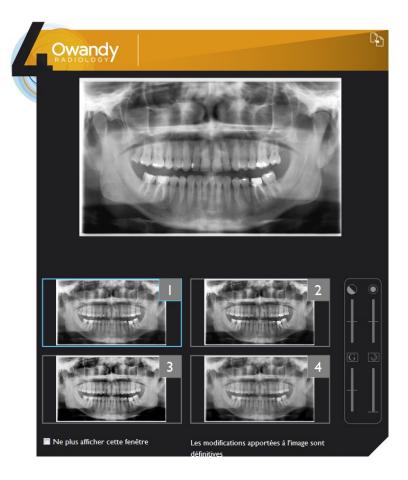


Main window with complete program selection menu, in extended view.





Main window with the image live preview





9. QUICKVISION 3D / FACE SCAN

The purpose of Face Scan is to facilitate communication with patients.

To do this, simply import a .PLY or .OBJ file, acquired using a third-party device, into the QuickVision 3D software and associate a 3D volume.











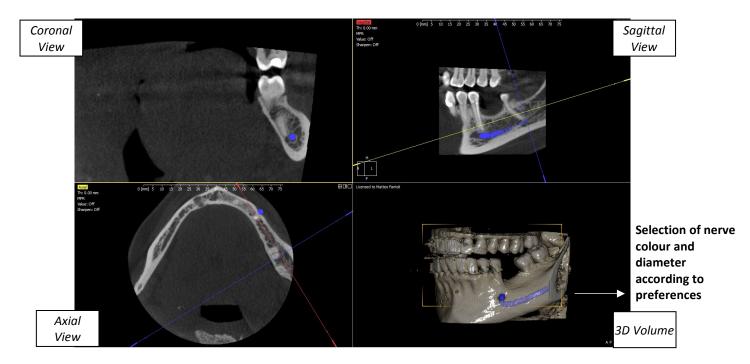
QuickVision 3D allows you to change densities to highlight bone structures and/or soft tissue.



10. QUICKVISION 3D

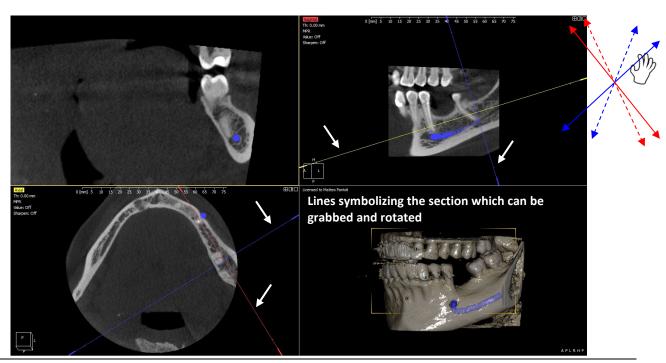
DICOM VIEWER

Independent rotation of the various axes in each of the 4 screens, to display the area required. Identifies the nerve and selects the right size and shape of implant.



Sectioning plans automatically default to coplanar views with the global system (axial, sagittal and coronal) Sectioning plan angles can be adjusted by entering the line relating to the section. Because these plans can be rotated, it's easy to analyse cross-sections from any position.

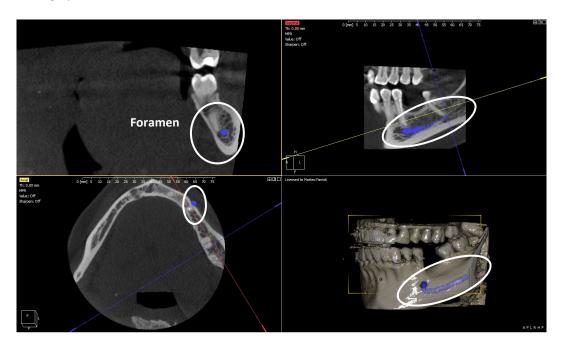
The original view can be restored by using the re-set command.





The mandibular nerve can be drawn in, to avoid touching it during the operation. 3 stages to obtain the mandibular nerve:

- Sectioning plan positioning so as to highlight foramina
- Selecting the point to highlight the section of the canal for various cross-sections
- Confirming operation



Option to create implants or import them from a library (Nobel®, etc.). Option to rotate radiological images around the implant.

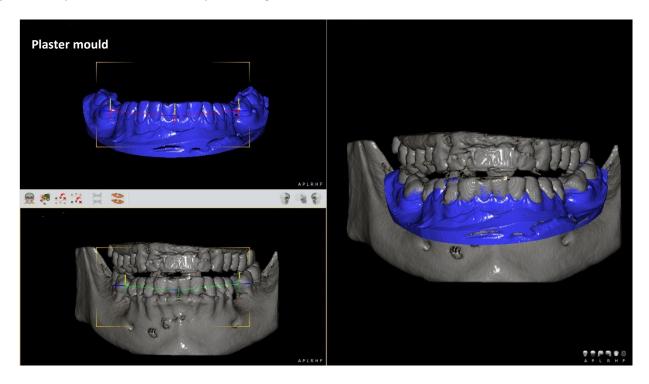




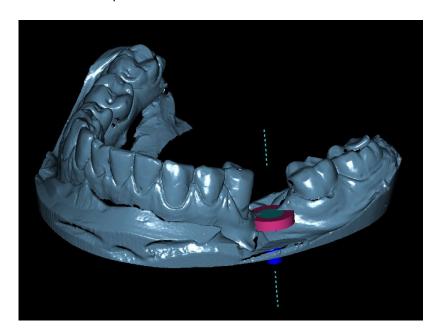
Overlaying

In this view, various objects can be overlaid when reconstructing the 3D patient volume.

This can be very useful, in order to correctly position the plaster mould used to model the surgical guide on, or to adjust the implant fixations or other positioning elements.

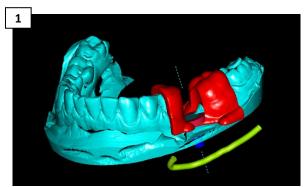


This can hide the reconstruction of the patient's 3D volume in order to be able to see one or more elements.

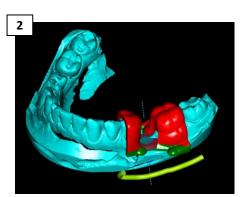




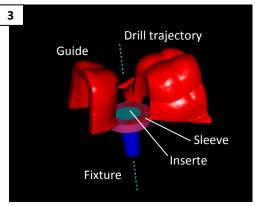
Surgical Guide Design



- Draw the mandibular nerve.
- Select the fixations, position them and adjust their size.
- Overlay the plaster model scan.
- Add the ring, the insert and the surgical guide.



• Finalize the surgical guide by adapting it to the plaster model.



• Select a view that will display the final model of the surgical guide.



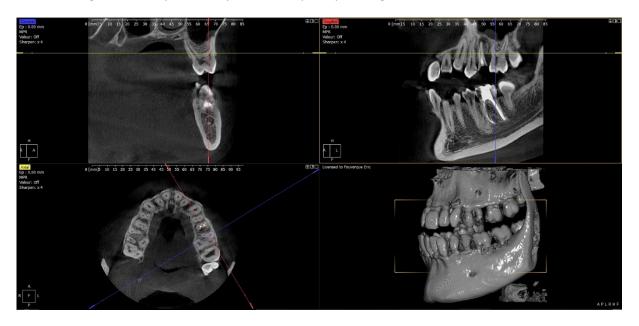
 Download the project in order to generate an STL file and to print your drill template in 3D.
 Alternatively, you can send the patient's plaster mould and 3D volume to the specialist centre, which will be able to both plan the implant and create the drill template for you.



11. 5 STAGES OF GUIDED SURGERY

STAGE 1 3D imaging to produce a DICOM image

- Full-mouth imaging in just one exposure (3D I-Max).
- Integrated and optimised system for implant planning.





STAGE 2 Create an STL file of the dental impression

• 4 méthods to obtain an STL file

Method 1

Traditional dental impression

↓

Create the plaster model

↓

Scan plaster model in a lab to obtain an STL file

↓

Import the STL file into QuickVision



Method 2

Traditional dental

impression

↓
Create the plaster
model
↓
Scan plaster model
with
I-Max 3D (DICOM)
↓
Convert the
DICOM file into an
STL file



Method 3

Traditional dental

impression

↓

Scan dental
impression with 3D

I-Max (DICOM)

↓

Convert the

DICOM file into an

STL file

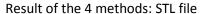


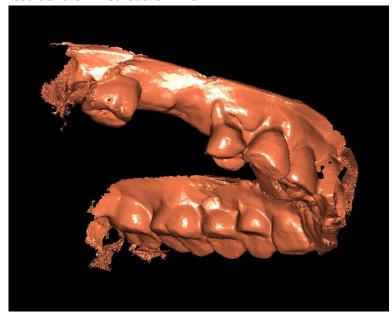
Method 4

Dental impression taken directly using an intraoral camera (STL file)

Umport the STL file into QuickVision









STAGE 3 QuickVision 3D : superposition, planification et création du guide

 Overlay DICOM and STL files to obtain a complete image with soft and hard tissue. Demo video available on our YouTube channel Owandy Radiology (Superimpositioning_OWANDY RADIOLOGY_QuickVision 3D)

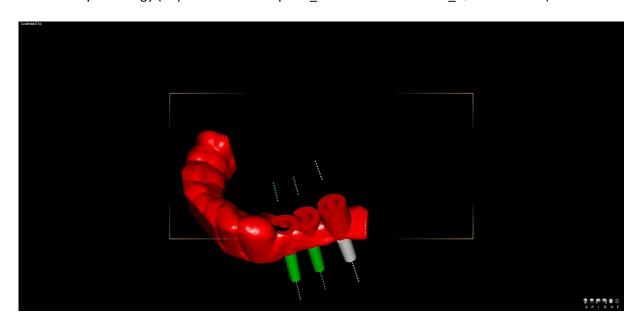


Quick, easy and intuitive implant treatment planning Demo video available on our YouTube channel
 Owandy Radiology (Implant create and place_OWANDY RADIOLOGY_QuickVision 3D)





Quick, easy and intuitive implant treatment planning Demo video available on our YouTube channel
 Owandy Radiology (Implant create and place_OWANDY RADIOLOGY_QuickVision 3D)





STAGE 4

3D printing of the surgical guide on a Form 2 (Formlabs) type printer, or by the laboratory

Top quality guided surgery.
Time-savings (no subcontracting).









STAGE 5 Implant placement: a safe and accurate surgical operation



The guide is placed in the mouth and its position controlled using the windows.





A circular scalpel is used to mark the gums, to carry out flapless surgery or, in this case, surgery with a small flap.





The implant is positioned using the guide, which ensures the perfect axial, vertical and rotational positioning with regard to the indexation.





The laboratory screw is removed.





The prosthetic is placed and screwed onto the implant. It finds the right position in alignment with the other teeth.



Connective tissue roll is used to repair gum tissue.



Stitches are done using PTFE 4/0 Cytoplast thread.
The occlusal command is used to check the underbite.



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